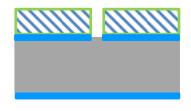
Silicon buried channels for Pixel detector cooling



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- The innovative idea is to integrate, into silicon electronics, of the cooling system based on a microchannels made by DRIE technology.
- ✓ The DRIE processes have the capability to create a geometry of the microchannel completely original which allows a subsequent step of sealing safer and more efficient in the pressure conditions expected during the hydraulic tests.
- ✓ This tech. permits the integration of the cooling system within the same detector with obvious advantages on the optimization of thermal bridges and transparency to the incident particles. Avoiding high temperature steps, the process is compatible with a CMOS device

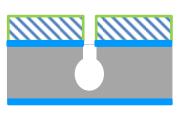
Fabrication Process



Define & etch SiO₂



DRIE anisotropic process



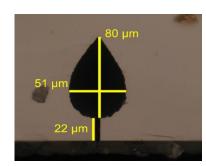
DRIE isotropic process

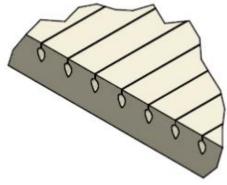


Sealing: PECVD deposition

Microchannel Geometry

Channels made with individual holes section is determined by the DRIE process, length determined by the layout





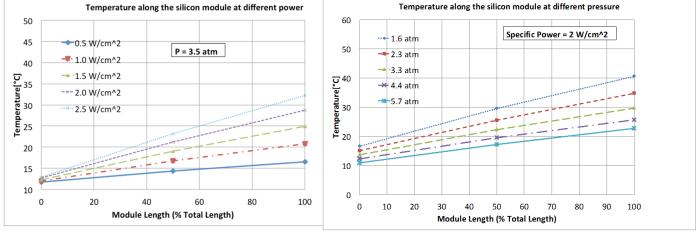
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- ✓ The experimental results show a general compliance of the temperature of the sample to the specific fixed at least up to a power of about 2.5 W/cm2 and also indicate at the same power, a strong dependence of the average temperature of the sample from the supply pressure of the fluid.
- ✓ Structural tests. The oxide layer that seals the microchannels resists at pressures greater than 100 atm (limit of the pump of the circuit).No damage is observed on the sample, setting a safety factor of about 30 compared to the pressure used in standard test.

Layout 1 (die 12.8 x 60 mm²):

- 80 channels
- hydr. diameter ~70um
- step 150um



Further developments:

- Optimize microchannel design: hydraulic diameter/pitch
- Special **microchannels with bidirectional flow** to be used to improve performance
- Realize microchannels on single silicon die
- Electrical characterization of microchannel-cooled CMOS FE chip

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